

### Claims

What is claimed is:

- 1 1. A socket contact, comprising:  
2 a first end, the first end having a simple geometry that is configured to  
3 interconnect with a load-generating device; and  
4 a second end, the second end having a contact pad of a complex geometry that  
5 is configured to enable placement and electrical coupling of a component between the  
6 socket contact and a substrate.
- 1 2. The socket contact of Claim 1, wherein the contact pad includes a first contact  
2 pad area and a second contact pad area.
- 1 3. The socket of Claim 2, wherein the second contact pad area is rectilinear and the  
2 first contact pad area is curvilinear.
- 1 4. The socket of Claim 2, wherein the first contact pad area is configured to couple  
2 to an interface configuration selected from a group including LGA, PGA, CSP, and BGA.
- 1 5. The socket of Claim 2, wherein the second contact pad area extends in a third  
2 dimension from the first contact pad area.
- 1 6. The socket of Claim 5, wherein the second contact pad area includes a pair of  
2 opposed contact pad areas configured to grippingly engage a component.

1 7. The socket of Claim 1, wherein the component is selected from a group including  
2 capacitors, resistors, diodes, and inductors.

1 8. The socket contact of Claim 1, wherein a plurality of socket contacts are  
2 electrically and mechanically interconnected with each other.

1 9. A system, comprising:  
2 a system substrate;  
3 a bus disposed on the system substrate to facilitate data exchange;  
4 a memory configured to store data, the memory disposed on the system  
5 substrate and coupled to the bus; and  
6 a socket coupled to the system substrate, the socket including:  
7 a body;  
8 a socket contact housed by the body, the socket contact including  
9 a first end, the first end having a simple geometry that is configured to  
10 interconnect with a load generating device; and  
11 a second end, the second end having a contact pad of a complex geometry  
12 that is configured to enable placement and electrical coupling of a  
13 component between the socket contact and a substrate.

1 10. The system of Claim 9, wherein the contact pad includes a first contact pad area  
2 and a second contact pad area.

1 11. The system of Claim 10, wherein the second contact pad area is rectilinear, and  
2 the first contact pad area is curvilinear.

1 12. The system of Claim 10 wherein the first contact pad area is configured to couple  
2 to an interface configuration is selected from a group including LGA, PGA, CSP, and  
3 BGA.

1 13. The system of Claim 10, wherein the second contact pad area extends in a third  
2 dimension from the first contact pad area.

1 14. The system of Claim 13, wherein the second contact pad area includes a pair of  
2 opposed contact pad areas configured to grippingly engage a component.

1 15. The system of Claim 9, wherein the component is selected from a group  
2 including capacitors, resistors, diodes, and inductors.

1 16. The system of Claim 9, wherein a plurality of socket contacts are electrically and  
2 mechanically interconnected with each other.

1 17. A socket connection, comprising:  
2 a substrate;  
3 a component, the component electrically coupled to the substrate; and

4 a socket body, the socket body including a plurality of socket contacts, each of  
5 the socket contacts including  
6 a first end configured to electrically couple with a load generating device, and  
7 a second end, the second end having a contact pad configured to enable  
8 placement and electrical coupling of the component between the contact  
9 second end and the substrate.

1 18. The socket connection of Claim 17, wherein the first end is of a simple geometry  
2 and the second end is of a complex geometry.

1 19. The socket connection of Claim 17, wherein the component is selected from a  
2 group including capacitors, resistors, diodes, and inductors.

1 20. A packaging method comprising:  
2 providing a substrate having a plurality of land pad;  
3 providing a socket having a plurality of socket contacts disposed therein, each of  
4 the socket contacts including a first end configured to electrically interface with a  
5 microelectronic package, and a second end configured to electrically interface with a  
6 corresponding land pad of the substrate, the second end having a contact pad  
7 configured to enable placement and electrical coupling of the component between the  
8 contact second end and the substrate;  
9 placing the socket onto the substrate;  
10 placing a component between the socket and the substrate; and

11 coupling the second end of the socket contact to the component and to the land  
12 pad of the substrate.

1 21. The method of Claim 20, wherein providing a socket having a plurality of socket  
2 contacts disposed therein includes configuring the first end to be a simple geometry and  
3 configuring the second end to be a complex geometry.

1 22 The method of Claim 20, further comprising coupling a microelectronic package  
2 to the socket.

1 23. The method of Claim 20, wherein the component is selected from a group  
2 including capacitors, resistors, diodes, and inductors.